

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Info
1	BRS	3	mesh and mems and carrier with back\$6 with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 11:05			0
2	BRS	5	mesh and mems and adhe\$6 with back\$6 with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 11:07			0
3	BRS	4	device with mesh and mems and back\$6 with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 11:08			0
4	BRS	10 7	mesh and mems and back\$6 with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:36			0
5	BRS	59	mesh and mems and back\$6 with substrate and (thin\$6 or grind\$ or reduc\$6) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 11:37			0
6	BRS	22	mems and back\$6 with substrate and (thin\$6 or grind\$ or reduc\$6 or polish\$6) with substrate and vent\$6 with hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 11:58			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Errors
7	BRS	3	mems and back\$6 with substrate and (thin\$6 or grind\$ or reduc\$6 or polish\$6) with substrate and vent\$6 with hole and (accoustic\$6 or loudspeaker or microphone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:01			0
8	BRS	3	mems and back\$6 with substrate and (thin\$6 or grind\$ or reduc\$6 or polish\$6) and vent\$6 with hole and (accoustic\$6 or loudspeaker or microphone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:02			0
9	BRS	1	mems and back\$6 with substrate with (thin\$6 or grind\$ or reduc\$6 or polish\$6) and vent\$6 with hole and (accoustic\$6 or loudspeaker or microphone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:03			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error
10	BRS	3	mems and back\$6 and substrate with (thin\$6 or grind\$ or reduc\$6 or polish\$6) and vent\$6 with hole and (accoustic\$6 or loudspeaker or microphone)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:03		0
11	BRS	2	mems and (bond\$6 or adhes\$8) and substrate with (thin\$6 or grind\$ or reduc\$6 or polish\$6) and vent\$6 with hole and (accoustic\$6 or loudspeaker or microphone)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:04		0
12	BRS	11	mems and (bond\$6 or adhes\$8) and substrate and (thin\$6 or grind\$ or reduc\$6 or polish\$6) and vent\$6 with hole and (accoustic\$6 or loudspeaker or microphone)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:16		0

	Type	Hits	Search Text	DBs	Time Stamp	Com ments	Er ror in fo r m a t i o n
13	BRS	17	mems and (bond\$6 or adhes\$8) and substrate with (thin\$6 or grind\$ or reduc\$6 or polish\$6) and vent\$6 with hole and (acoustic\$6 or loudspeaker or microphone)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:58		0
14	BRS	31	mems and (bond\$6 or adhes\$8) and substrate and (thin\$6 or grind\$ or reduc\$6 or polish\$6) and vent\$6 with hole and (acoustic\$6 or loudspeaker or microphone)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:34		0
15	IS& R	2	("5658710").PN .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:37		0
16	IS& R	2	("5717631").PN .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:37		0
17	IS& R	2	("5970315").PN .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:39		0
18	IS& R	2	("6100477").PN .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:55		0
19	IS& R	2	("6262946").PN .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:56		0

	Type	Hits	Search Text	DBs	Time Stamp	Com ments	Er rors
20	BRS	679	(438/459).ccls .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 13:03		0
21	BRS	18	(438/459).ccls . and mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 12:59		0
22	BRS	2	(438/459).ccls . and mesh and carrier with back\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 13:10		0
23	BRS	9	(438/459).ccls . and mesh and carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 13:00		0
24	BRS	0	(438/459).ccls . and vent\$ near hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 13:03		0
25	BRS	1	(438/459).ccls . and vent\$ with hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 13:04		0
26	BRS	6	(438/459).ccls . and vent\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 13:06		0
27	BRS	42	(438/459).ccls . and mems	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 13:06		0
28	BRS	2	(438/459).ccls . and mems and mesh\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 13:06		0
29	BRS	9	(438/459).ccls . and mesh and carrier and back\$6 and (thin\$ or grind\$ or polish\$)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/24 13:06		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Errors
30	BRS	5	(438/459).ccls . and mesh and carrier and back\$6 and (thin\$ or grind\$ or polish\$) and (cut\$6 or dic\$6 or singulat\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 13:15			0
31	BRS	9	(438/459).ccls . and mesh and carrier and back\$6 and (thin\$ or grind\$ or polish\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/24 13:08			0
32	BRS	11 7	mesh and mems and carrier and (thining or grinding or backgrinding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 12:58			0
33	BRS	14 1	mesh and mems and carrier and (thinning or grinding or backgrinding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 12:59			0
34	BRS	38	mesh and mems and carrier and (thinning or grinding or backgrinding) and mask\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 13:31			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Ratio
35	BRS	0	mesh and carrier with substrate with backside with (attach\$6 or adhe\$8) and (thinning or grinding or backgrinding) with (substrate or wafer) and mask\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 13:35			0
36	BRS	8	mesh and carrier with (substrate or wafer) with (attach\$6 or adhe\$8) and (thinning or grinding or backgrinding) with (substrate or wafer) and mask\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 13:36			0
37	BRS	19	mesh and mems and carrier and (thinning or grinding or backgrinding) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 13:52			0
38	BRS	1	mesh and mems and substrate with (thinning or grinding or backgrinding) and wafer near carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 13:54			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Confirmation
39	BRS	12	mems and substrate with (thinning or grinding or backgrinding) and wafer near carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 14:42		0
40	BRS	36 0	substrate with (thinning or grinding or backgrinding) and (wafer or carrier) with (bond\$6 or attach\$6 or adhe\$8) with back\$8 with (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 14:45		0
41	BRS	26 5	substrate with (thinning or grinding or backgrinding) and (wafer or carrier) with (bond\$6 or attach\$6 or adhe\$8) with back\$8 with (substrate or wafer) and substrate with device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 14:46		0



	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Errors
42	BRS	25	substrate with (thinning or grinding or backgrinding) and (wafer or carrier) with (bond\$6 or attach\$6 or adhe\$8) with back\$8 with (substrate or wafer) and substrate with device and (cut\$6 or dic\$6 or singulat\$6) and (mem or mesh\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 14:50			0
43	BRS	50	substrate with (thinning or grinding or backgrinding) and (wafer or carrier) with (bond\$6 or attach\$6 or adhe\$8) with back\$8 with (substrate or wafer) and substrate with device with plurality	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 15:10			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Ratio
44	BRS	183	substrate with (thinning or grinding or backgrinding) and (wafer or carrier) with (bond\$6 or attach\$6 or adhe\$8) with back\$8 with (substrate or wafer) and substrate with device and (cut\$6 or dic\$6 or singulat\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:33		0
45	BRS	4	(wafer or carrier or die) with (bond\$6 or attach\$6 or adhe\$8) with back\$8 with (substrate or wafer or die) and mem and <del>cmos and mesh\$</del>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:40		0
46	BRS	36	(wafer or carrier or die) with (bond\$6 or attach\$6 or adhe\$8) with (substrate or wafer or die) and mem and <del>cmos and mesh\$</del>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:40		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Ratio
47	BRS	10	substrate with (thinning or grinding or backgrinding) and (wafer or carrier) with (bond\$6 or attach\$6 or adhe\$8) with back\$8 with (substrate or wafer or die) and mem and cmos	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:40			0
48	BRS	10	substrate with (thinning or grinding or backgrinding) and (wafer or carrier or die) with (bond\$6 or attach\$6 or adhe\$8) with back\$8 with (substrate or wafer or die) and mem and cmos	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:45			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error
49	BRS	5	(substrate or wafer or die or carrier) with (thinning or grinding or backgrinding) and (wafer or carrier or die or substrate) with (bond\$6 or attach\$6 or adhe\$8) with (substrate or wafer or die or carrier) and mem and cmos and mesh\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:49		0
50	BRS	2	(substrate or wafer or die or carrier) with (thinning or grinding or backgrinding) and (wafer or carrier or die or substrate) with (bond\$6 or attach\$6 or adhe\$8) with (substrate or wafer or die or carrier) and mem and cmos and (microphone\$ or loudspeaker\$ or accoustic\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 16:01		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Indication
51	BRS	3	(substrate or wafer or die or carrier) and (thinning or grinding or backgrinding) and (bond\$6 or attach\$6 or adhe\$8) with (substrate or wafer or die or carrier) and mem and cmos and (microphone\$ or loudspeaker\$ or accoustic\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 16:07		0
52	BRS	41	(substrate or wafer or die or carrier) and (thinning or grinding or backgrinding) and (bond\$6 or attach\$6 or adhe\$8) and mem and cmos and (microphone\$ or loudspeaker\$ o	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 16:08		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Errors
53	BRS	0	(substrate or wafer or die or carrier) and (thinning or grinding or backgrinding) and (bond\$6 or attach\$6 or adhe\$8) and mem and cmos and (microphone\$ or loudspeaker\$ or accoustic\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 16:08		0
54	BRS	34	(substrate or wafer or die or carrier) and (thinning or grinding or backgrinding) and (bond\$6 or attach\$6 or adhe\$8) and mem and cmos and (microphone\$ or loudspeaker\$ or accoustic\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 16:15		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error
55	BRS	109	(substrate or wafer or die or carrier) with (thinning or grinding or backgrinding) and (wafer or carrier or die or substrate) with (bond\$6 or attach\$6 or adhe\$8) with (substrate or wafer or die or carrier) and mem and cmos	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 16:16		0
56	BRS	200	mesh and mems and carrier and (thinn\$ or grinding or backgrinding or shaving or back adj grinding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 10:47		0
57	BRS	11	mesh and mems and carrier and (((thinn\$ or grinding or shaving) with back) or backgrinding or back adj grinding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 10:41		0
58	BRS	8	mesh and mems and carrier and (thinn\$ near back or grinding near back or backgrinding or shaving near back or back adj grinding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 10:46		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Errors
59	BRS	62	mesh and mems and carrier and (thinn\$ or grinding or backgrinding or shaving or back adj grinding) and vents\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:17			0
60	BRS	2	mesh and mems and (carrier or support\$ or reinforc\$) near (wafer or substrate) and (thinn\$ or grinding or backgrinding or shaving or back adj grinding) and vents\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:19			0
61	BRS	20	mesh and mems and (carrier or support\$ or reinforc\$) near (wafer or substrate) and (thinn\$ or grinding or backgrinding or shaving or back adj grinding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:50			0



	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error
62	BRS	3	mesh and mems and (carrier or support\$ or reinforc\$) near (wafer or substrate) same (thinn\$ or grinding or backgrinding or shaving or back adj grinding) same (attach\$ or bond\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:57		0